

Abstract of Disclosure

HEAT DISSIPATION APPARATUS UTILIZING EMPTY COMPONENT SLOT

[0037] A heat dissipation apparatus includes a heat transfer base that is operable to couple to a heat producing component that is operable to couple to a first component connector and be located in a first component slot defined by the first component connector, wherein the first component connector is located adjacent to and spaced apart from a second component connector that defines a second component slot. A heat dissipating member extends from the heat transfer base such that the heat dissipating member is located in the second component slot that is defined by the second component connector when the heat producing component is coupled to the first component connector and located in the first component slot. The heat dissipation apparatus may be coupled to a heat producing component and used to dissipate heat from the heat producing component when there are empty component connector slots located adjacent the component connector that the heat producing component is coupled to.

Fig. 3a

